



Prototype Development of a GEM-TPC for the SuperFRS

OUTLINE

- Introduction and Motivation
- GEM Technology and Characterization
- First GEM-TPC Prototype HB1 - Tests
- Second Prototype HB2 - AFTER Readout electronics
- Third Prototype HB3 - Xyter Readout electronics
- Active Divider for GEM-TPC
- Open Questions and TODO List

INTRODUCTION

FAIR is Facility for Antiproton and Ion Research. The concept of the FAIR Facility aims for a multifaceted forefront science program, beams of stable and unstable nuclei as well as antiprotons in a wide range of intensities and energies, with optimum beam qualities



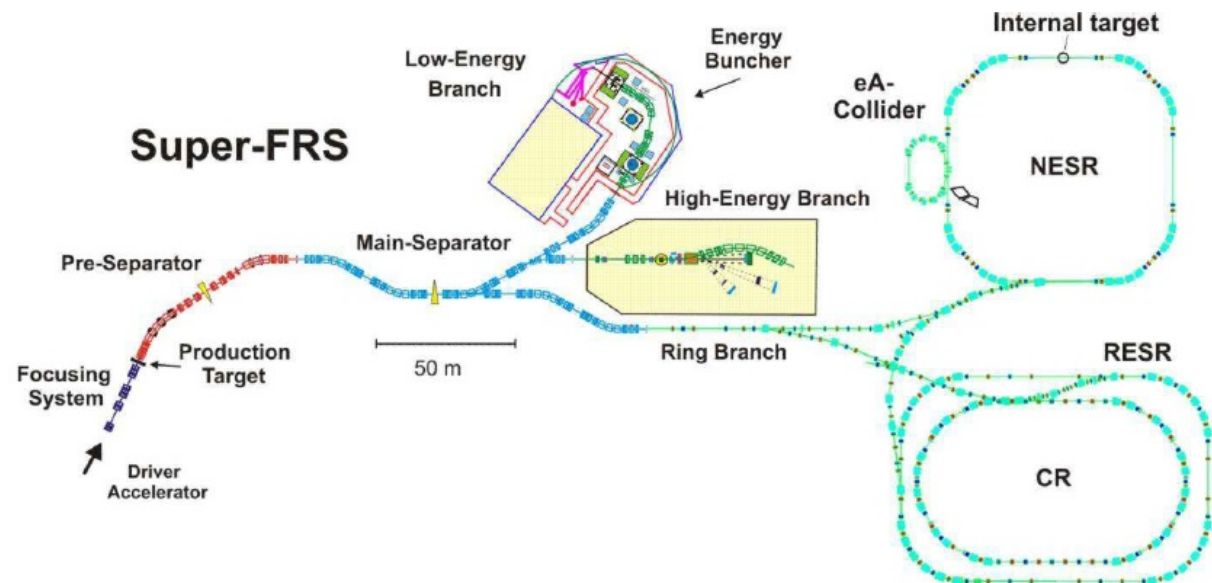
Time Table spans till end 2018

MOTIVATION

NUSTAR collaboration (Nuclear Structure, Astrophysics, and Reactions) has more than 700 members in total.

Part of the Finnish Contribution will be in the superconducting in-flight separator (Super-FRS) Diagnostic systems

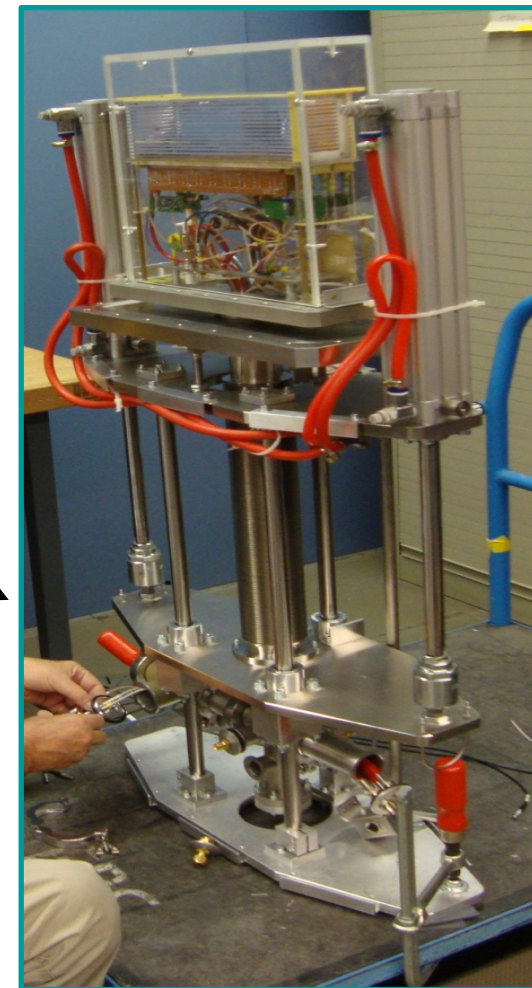
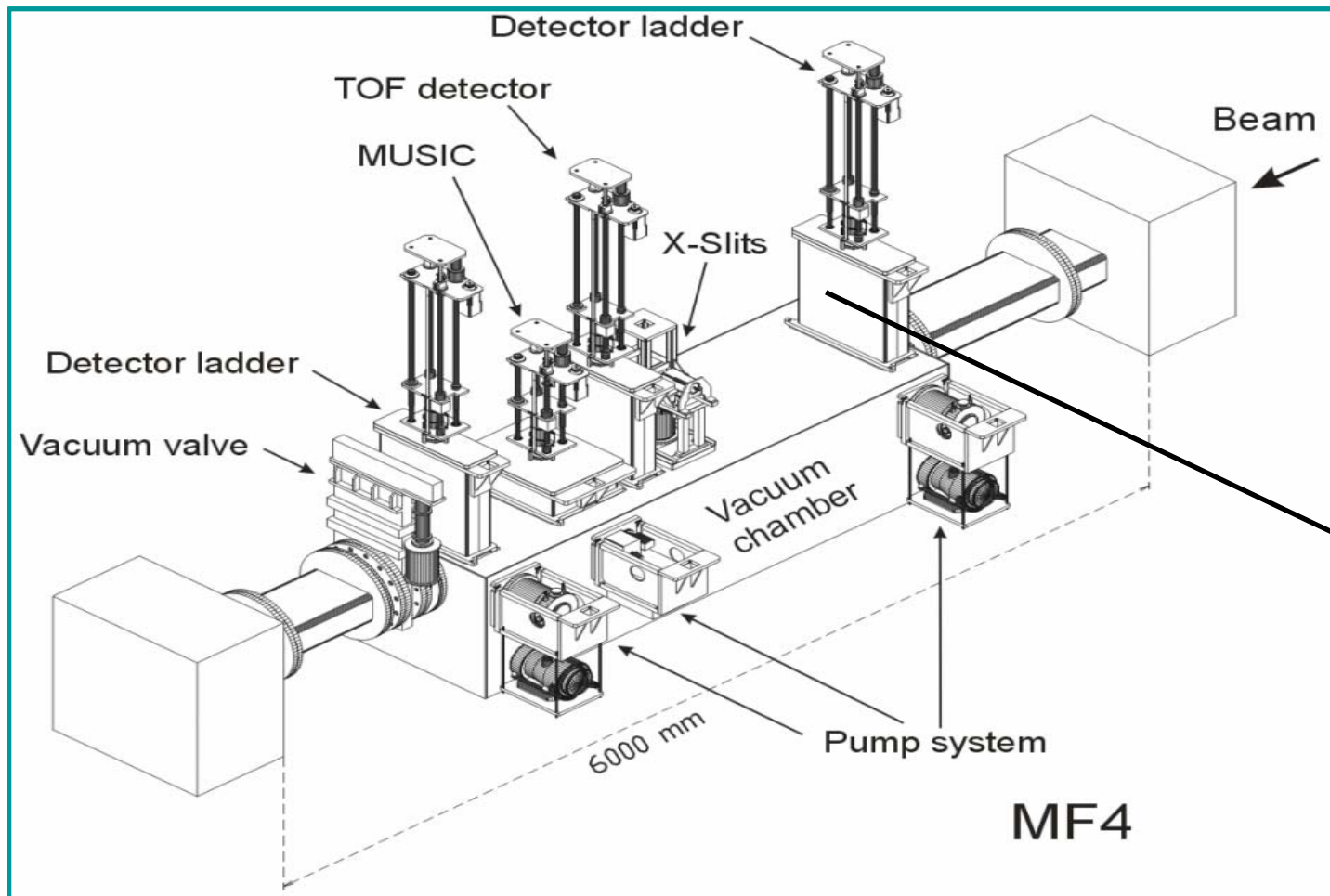
The NUSTAR Facility at FAIR
(The 3 Branches of the Super-FRS)



NUSTAR = Nuclear Structure, Astrophysics and Reactions

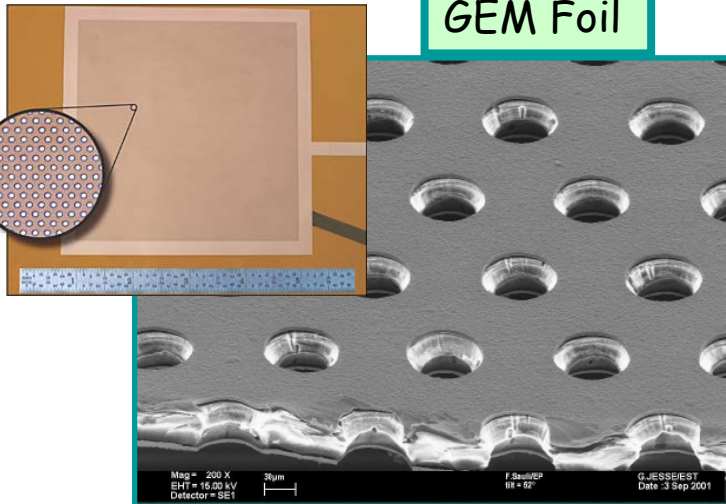
MOTIVATION (cont.)

DIAGNOSTIC SYSTEM STATION

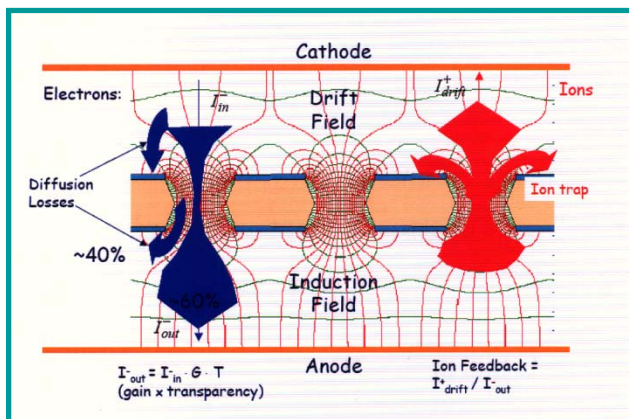


GEM TECHNOLOGY and CHARACTERIZATION

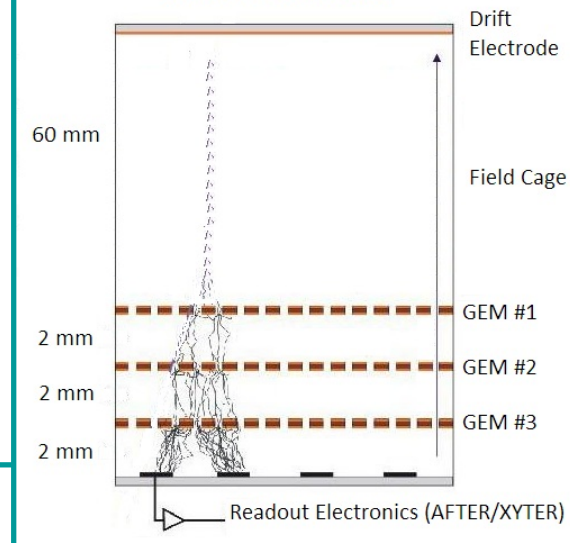
GEM Foil



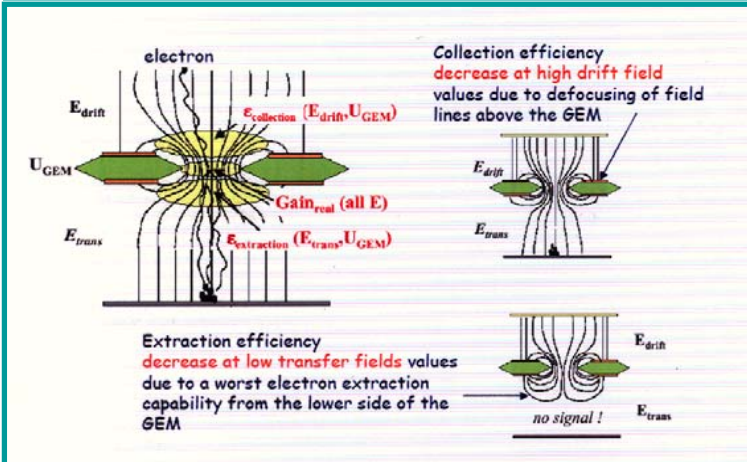
GEM Operation Principle



GEM-TPC LAYOUT

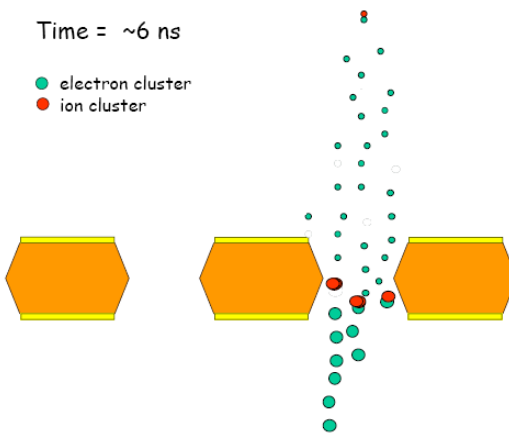


Extraction of the Electron Cloud and Signal Induction



Time = ~6 ns

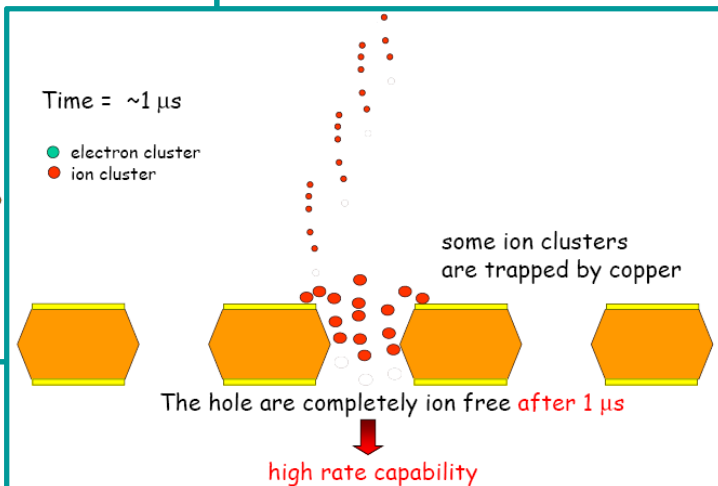
- electron cluster
- ion cluster



Avalanche development in time domain

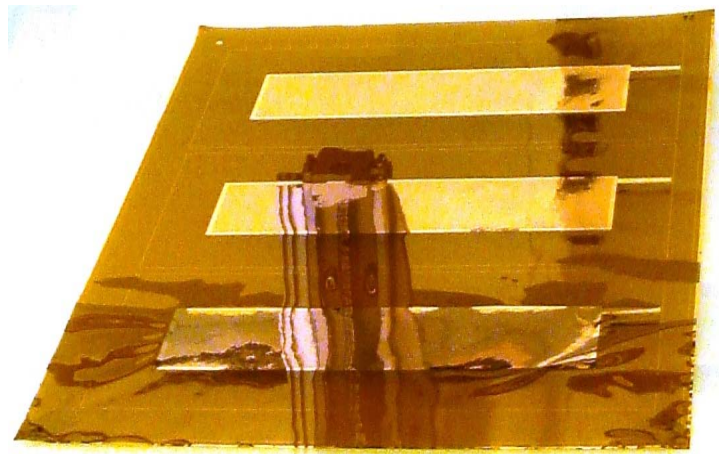
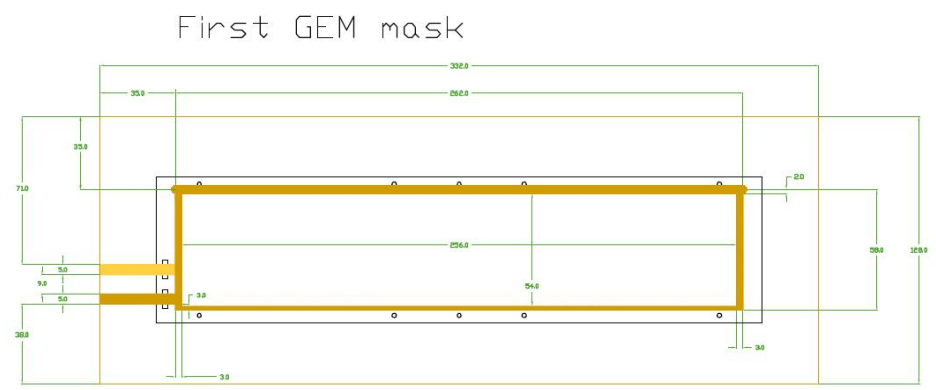
Time = ~1 µs

- electron cluster
- ion cluster

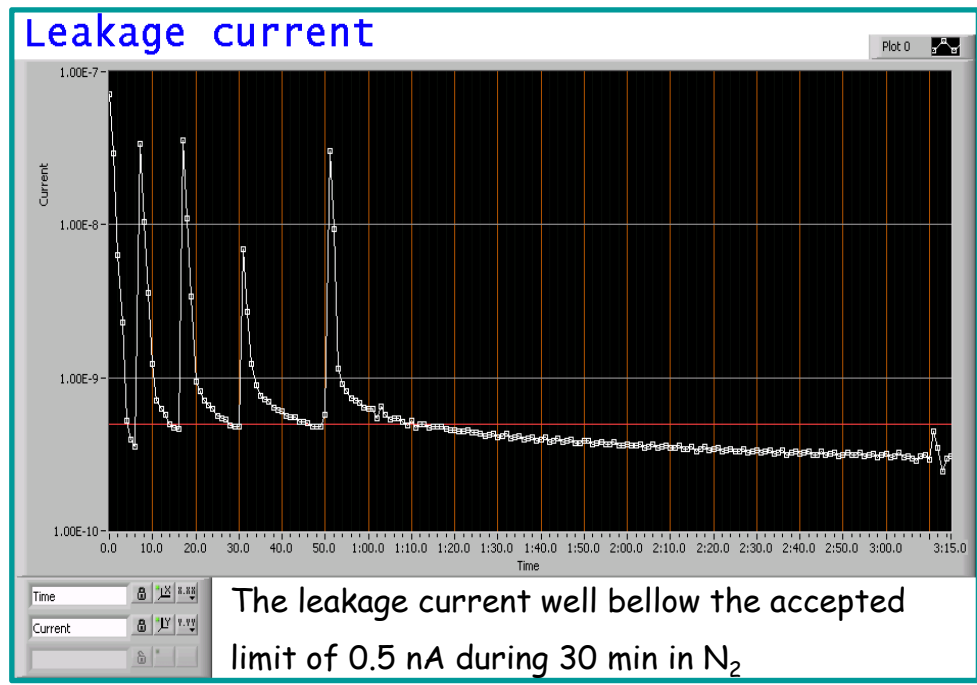


GEM TECHNOLOGY and CHARACTERIZATION (cont.)

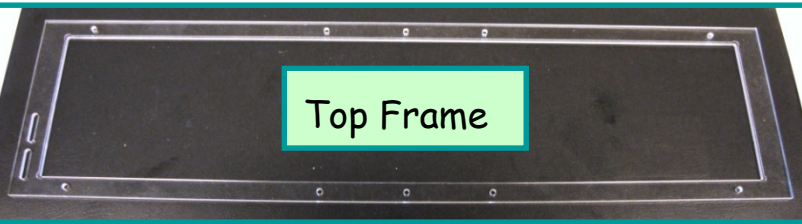
GEM mask designed at HIP and manufacture at CERN - workshop (Rui de Oliveira)



GEM Foil

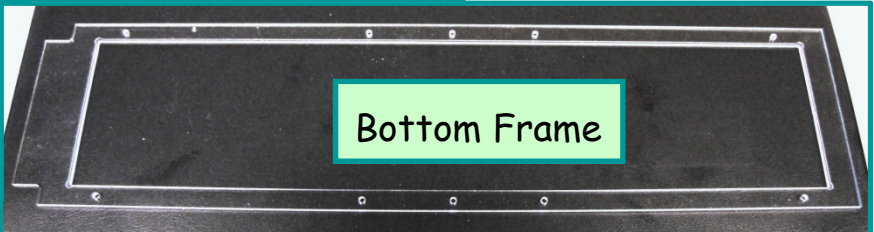


GEM TECHNOLOGY and CHARACTERIZATION (cont.)



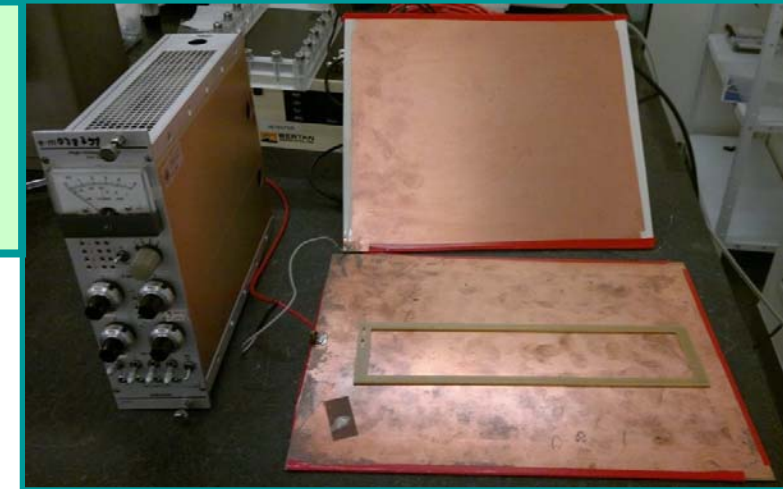
Top Frame

First mechanical models for the top and Bottom frames

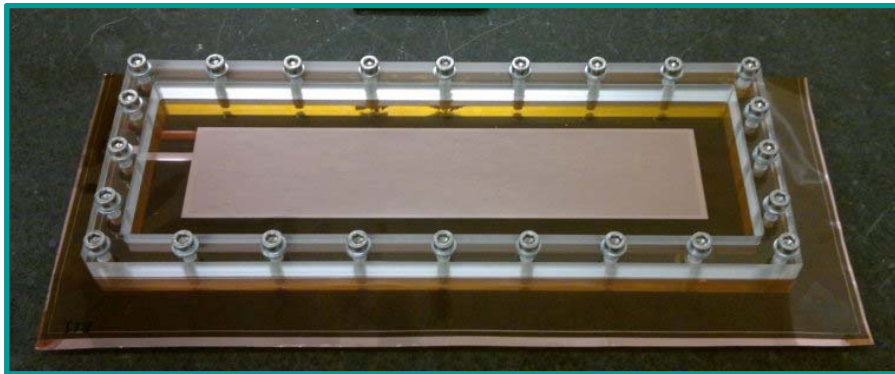


Bottom Frame

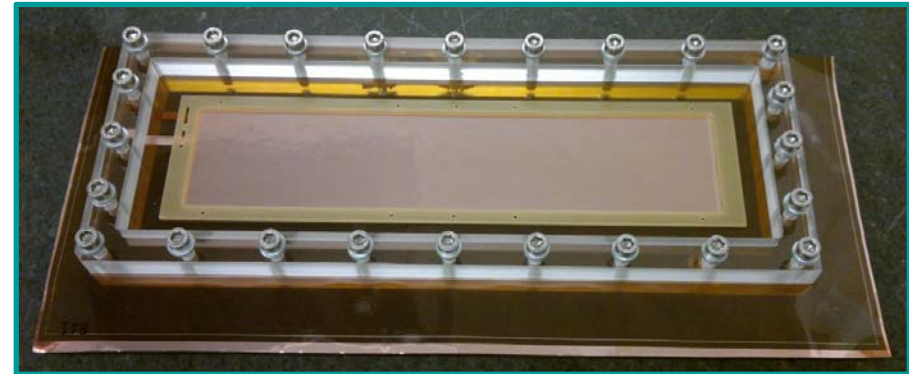
Electrostatic Test for all the frames @ 3 kV
Possible breakdowns corrected with Nuvovern



GEM Foils stretcher - No repels or undulation visible



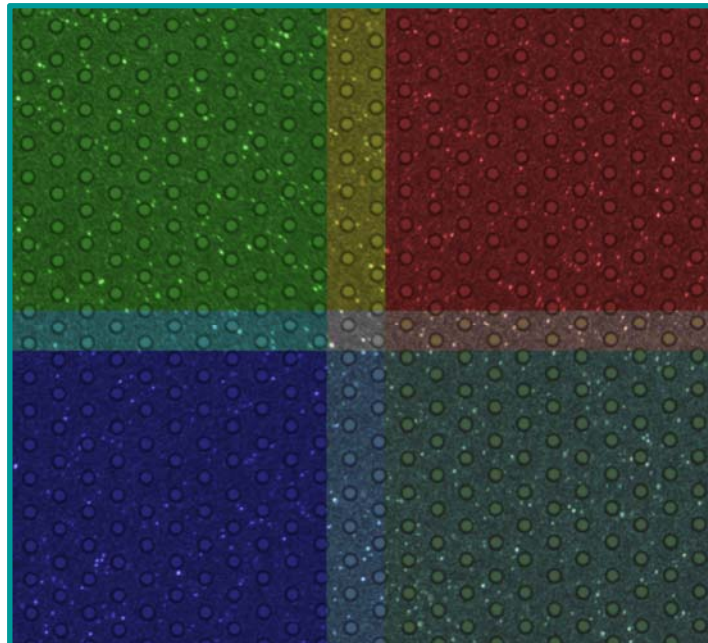
Top frame glued to the GEM foil, after cured in oven



GEM TECHNOLOGY and CHARACTERIZATION (cont.)

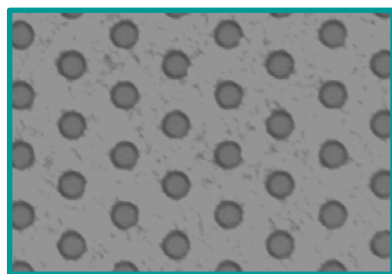
FOUR images Stitched

The overlapping
on these images
is of 245 μm
and 140 μm



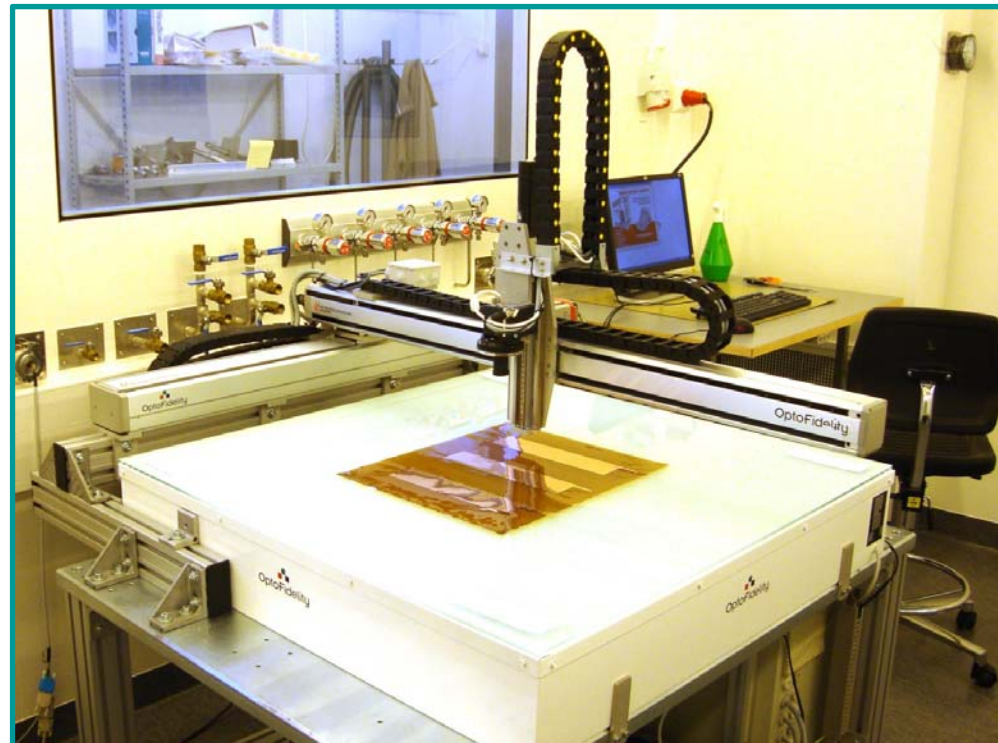
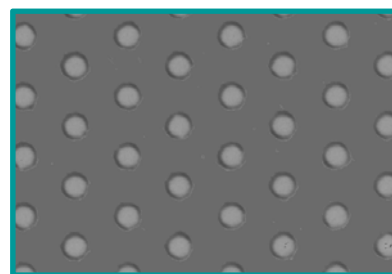
After Apply Red Filter

This procedure is used to find
defects and to find the outer
diameter of the holes



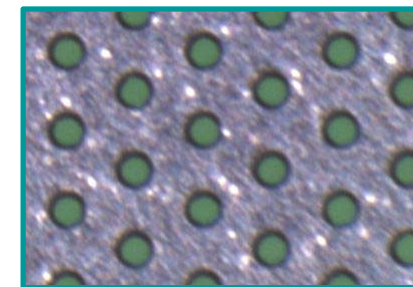
After Apply Green Filter

This procedure is used to find
blind holes and to measure the
inner diameter of the holes

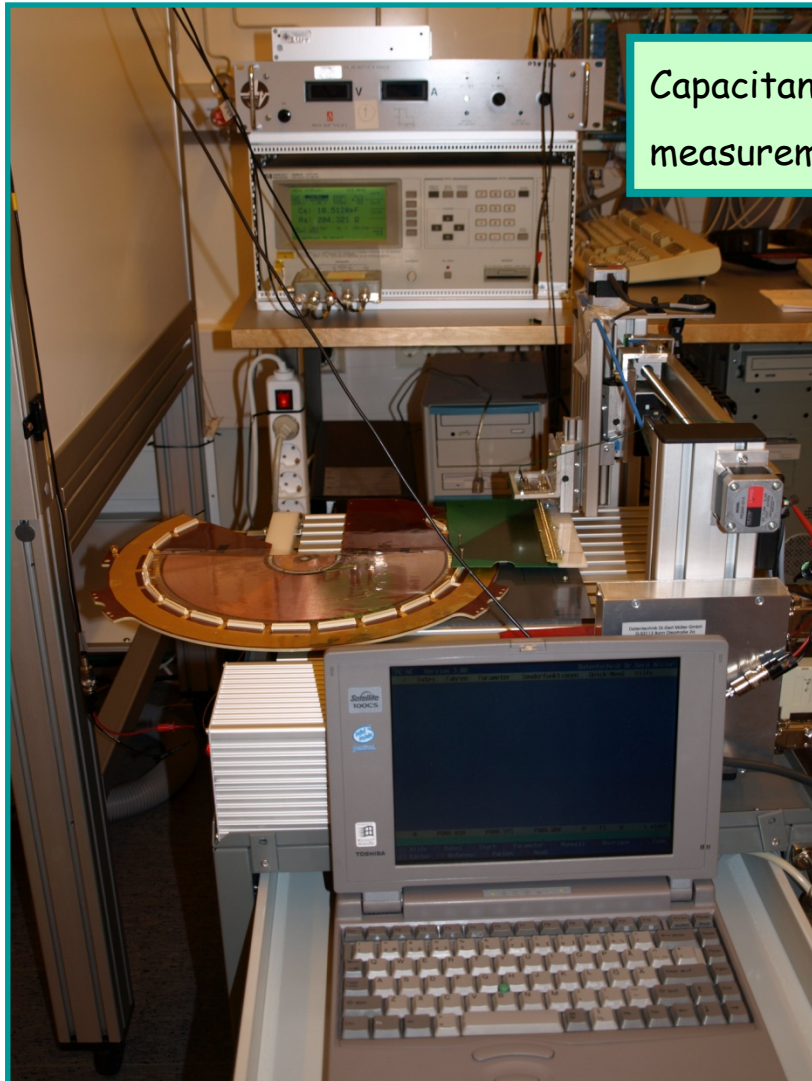


New System

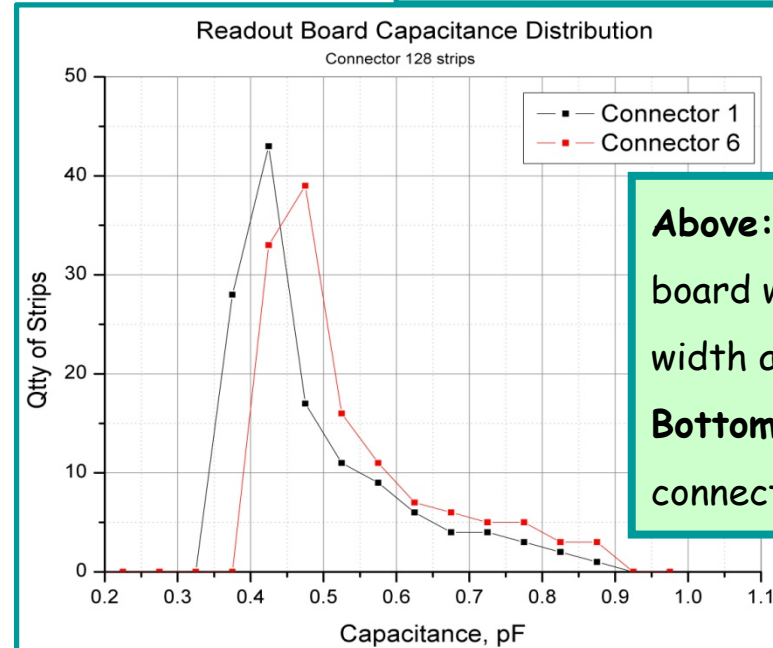
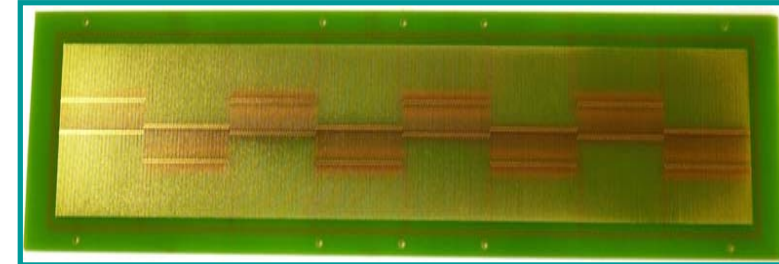
Based on 9 Mpix camera with
integrated telecentric optics for
this setup one pixel corresponds
to 1.7 x 1.7 microns



GEM TECHNOLOGY and CHARACTERIZATION (cont.)



Capacitance measurement setup



Above: The electrodes of the board with strips of 200 μm width and 500 μm pitch
Bottom: 8 Header Panasonic connectors with 130 Pin each



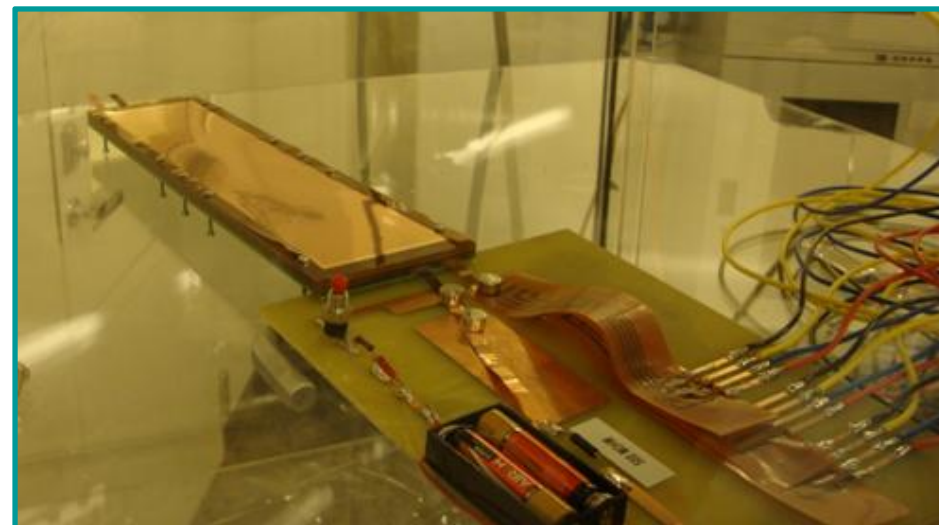
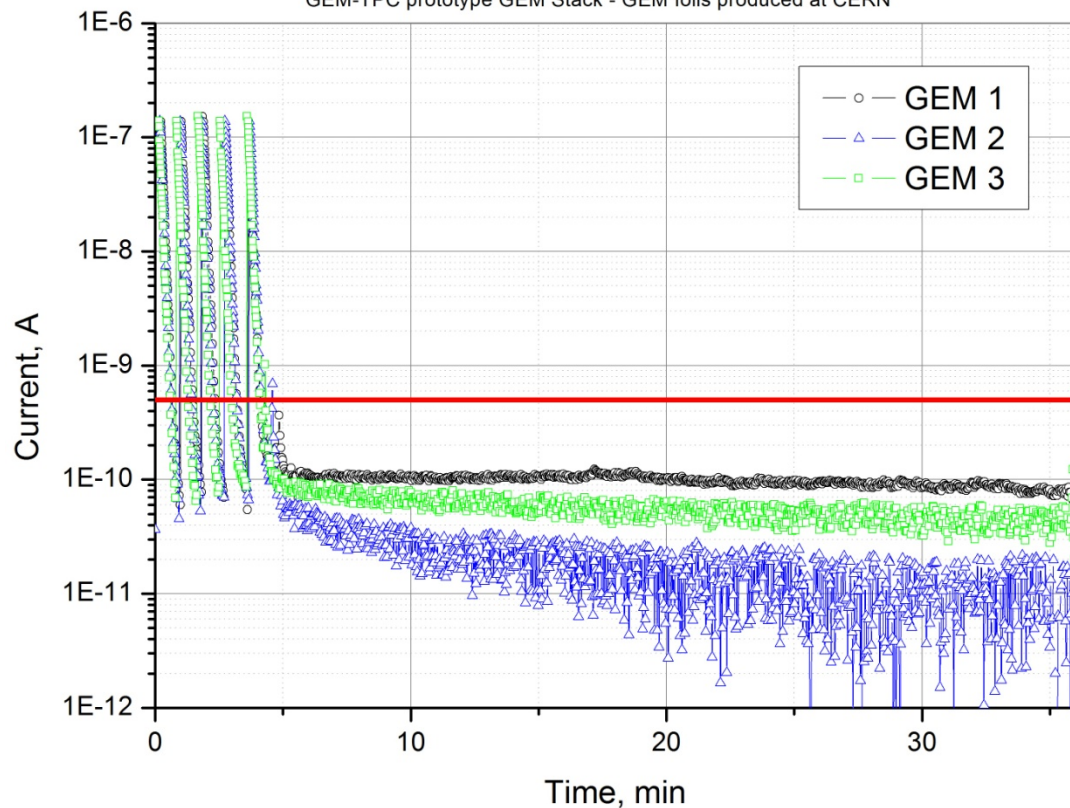
GEM TECHNOLOGY and CHARACTERIZATION (cont.)

GEM Stack tests:

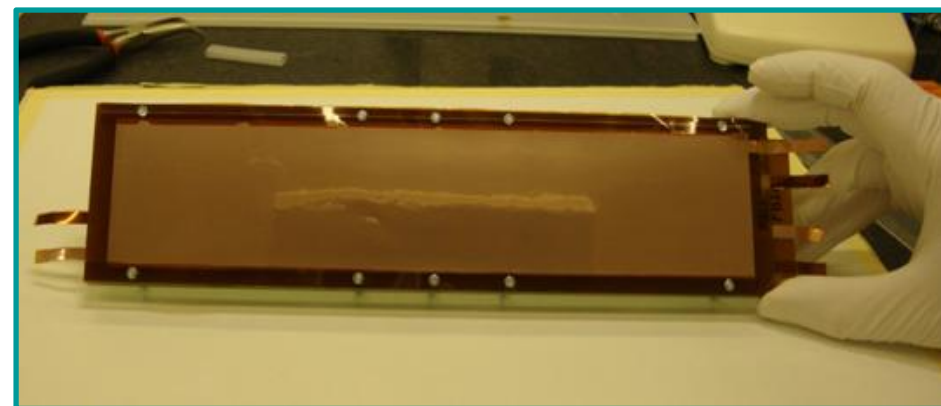
Triple GEM leakage current measurements

Leakage Current Measurement

GEM-TPC prototype GEM Stack - GEM foils produced at CERN



GEM Stack for the GEM-TPC prototype HB2



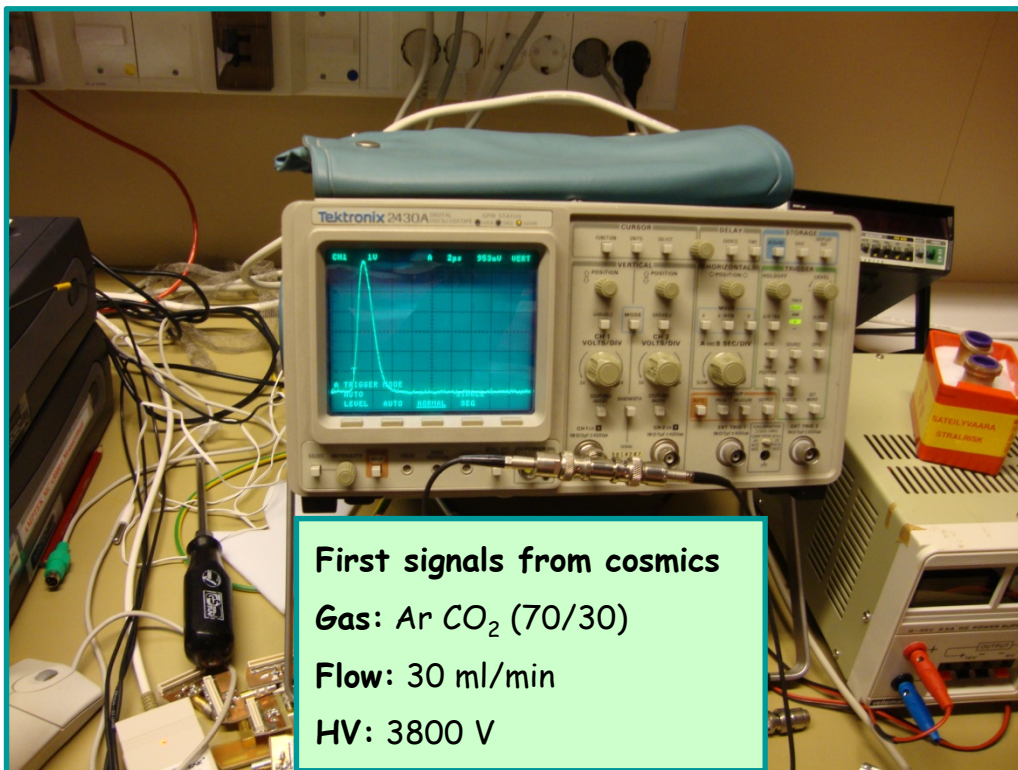
GEM TECHNOLOGY and CHARACTERIZATION (cont.)

GEM Stack tests:

Preliminary measurements in the lab; the radiation used for these tests was the ^{55}Fe and cosmics

GEM Stack test bench

The GEM stack was assembled as a triple GEM detector with 3 mm of Drift

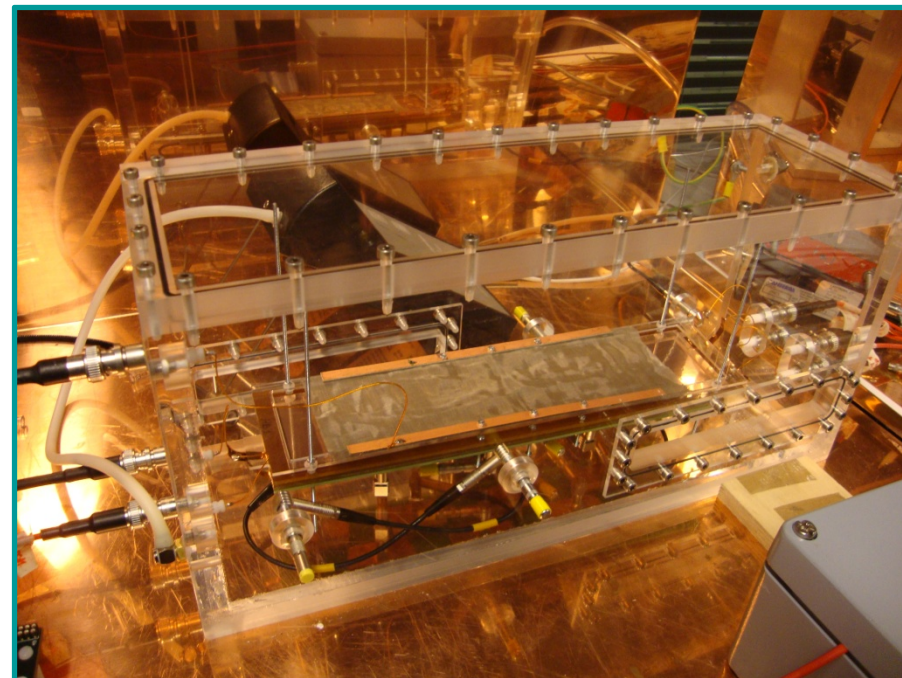


First signals from cosmics

Gas: Ar CO₂ (70/30)

Flow: 30 ml/min

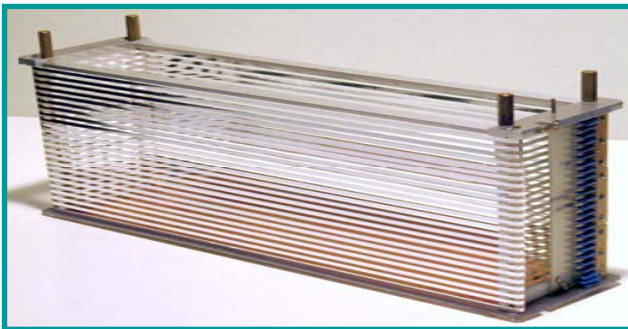
HV: 3800 V



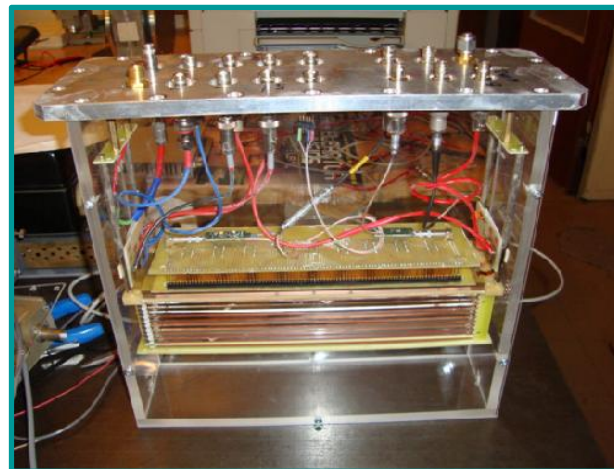
FIRST GEM-TPC PROTOTYPE HB1 - TEST

Tests and assembling at Comenius University - Bratislava

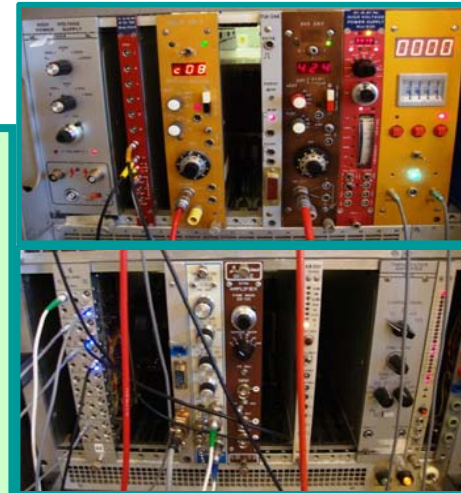
Field cage of 60 mm drift



Flange the GEM-TPC
HB1 equipped with
delayed lines



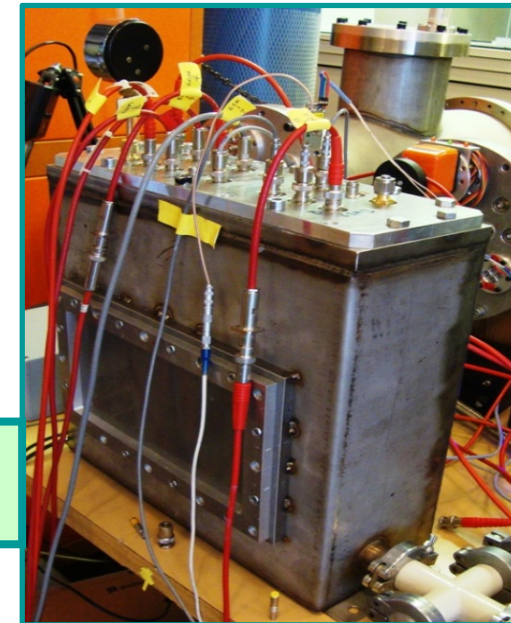
HV Power
Suppliers.
TDC module.
Source 1D
movement
controller.
Shaper module.
Linear
Amplifiers.
CAMAC crate



GEM Stack integration

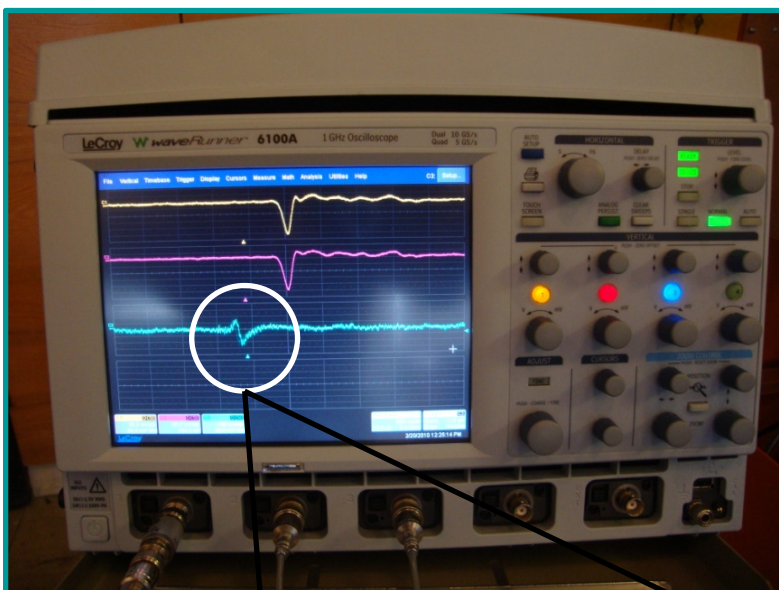


First GEM-TPC
detector



FIRST GEM-TPC PROTOTYPE HB1 - TEST

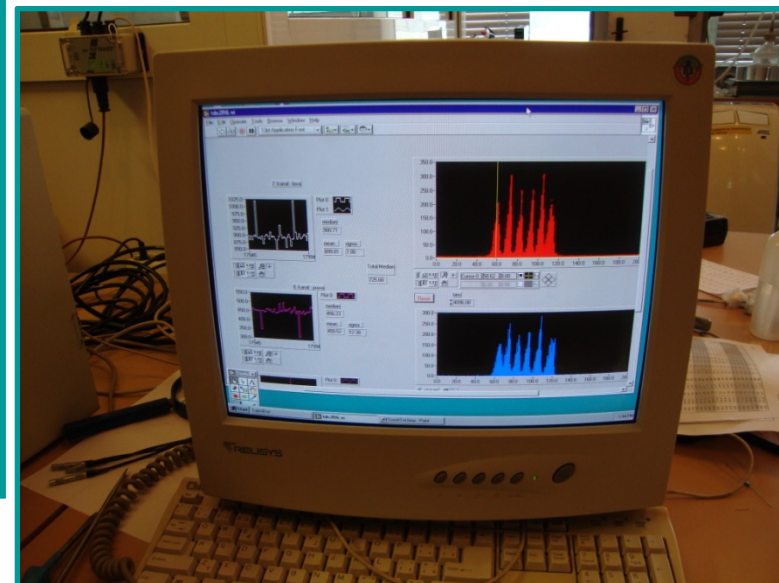
GEM-TPC test in lab at Comenius University



It can be observed:

- Signals from the delayed lines are very clean
- Same relative time between them
- Trigger signal bipolar, it can be that the 40% negative overshoot is due to e-transparency losses in the GEM 3

GEM-TPC tracking capabilities for ^{55}Fe



In the picture above there are multiple picks from the different source positions. The source was not very well collimated therefore a mm scale resolution on X was achieved and the trigger was taken from the bottom of the GEM3



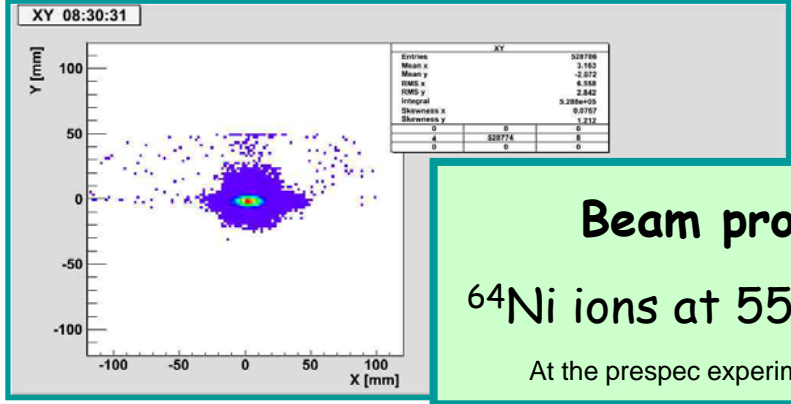
Trigger Signal before reshaping



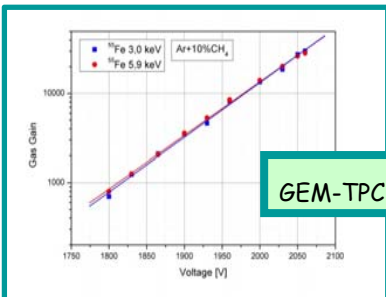
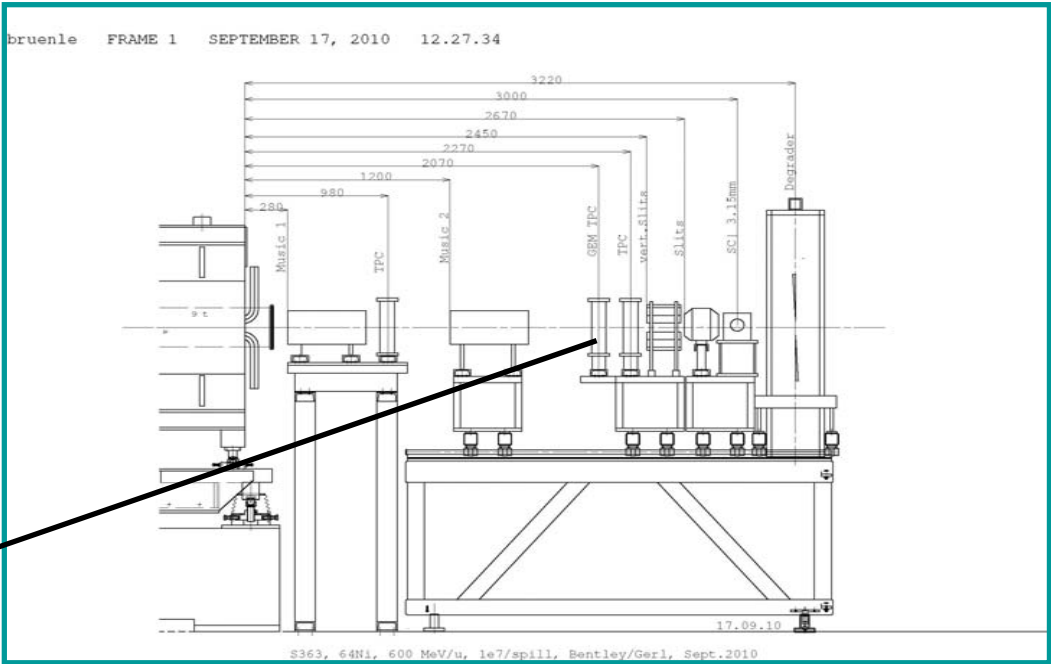
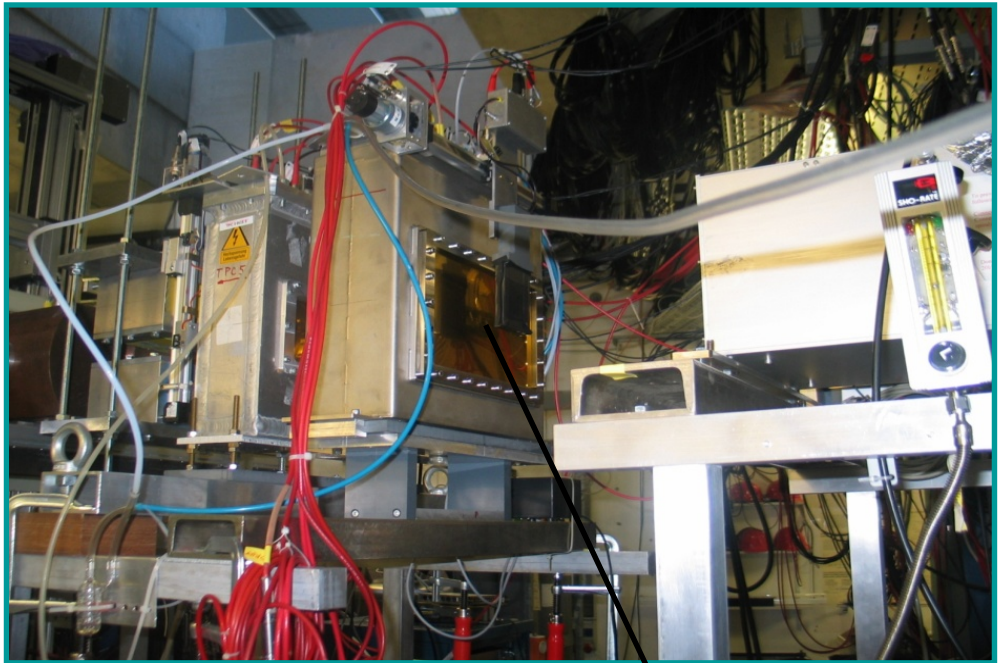
Trigger Signal with rise and decay time reshaped

FIRST GEM-TPC PROTOTYPE HB1 - TEST (cont.)

GEM-TPC Beam test at GSI - Darmstadt



Beam profile
 ^{64}Ni ions at 550 MeV/u
 At the prespec experiment - S363



GEM-TPC Gain

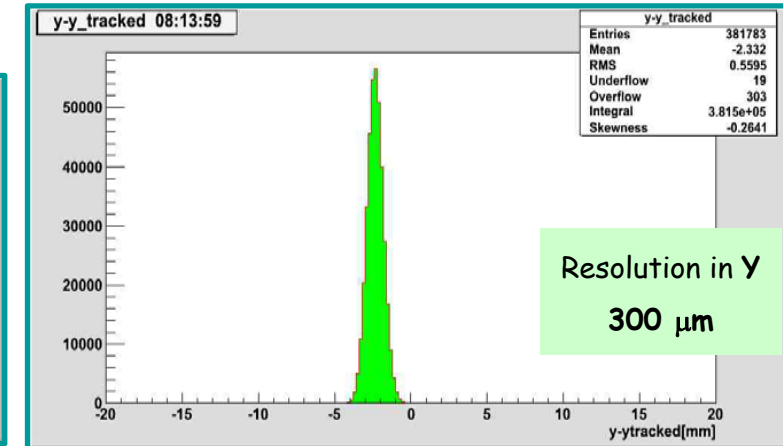
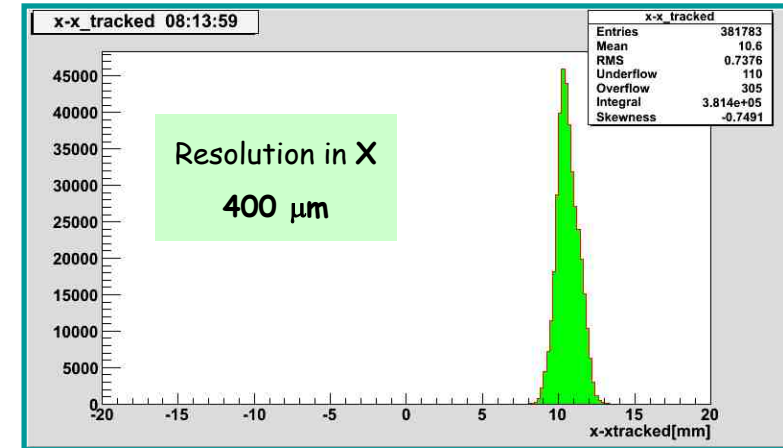
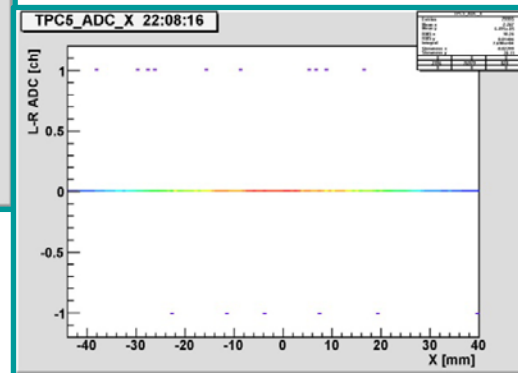
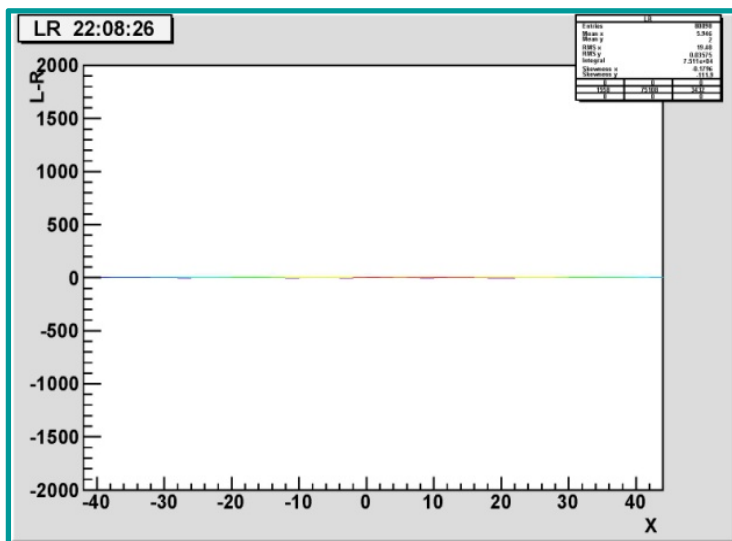
GEM-TPC at S4

FIRST GEM-TPC PROTOTYPE HB1- TEST (cont.)

GEM-TPC Beam test Results

On the bottom after applying corrections for the preAmps nonlinearities, we can observe that the response is uniform along the full sensitive volume.

GEM-TPC response in X and Y coordinates

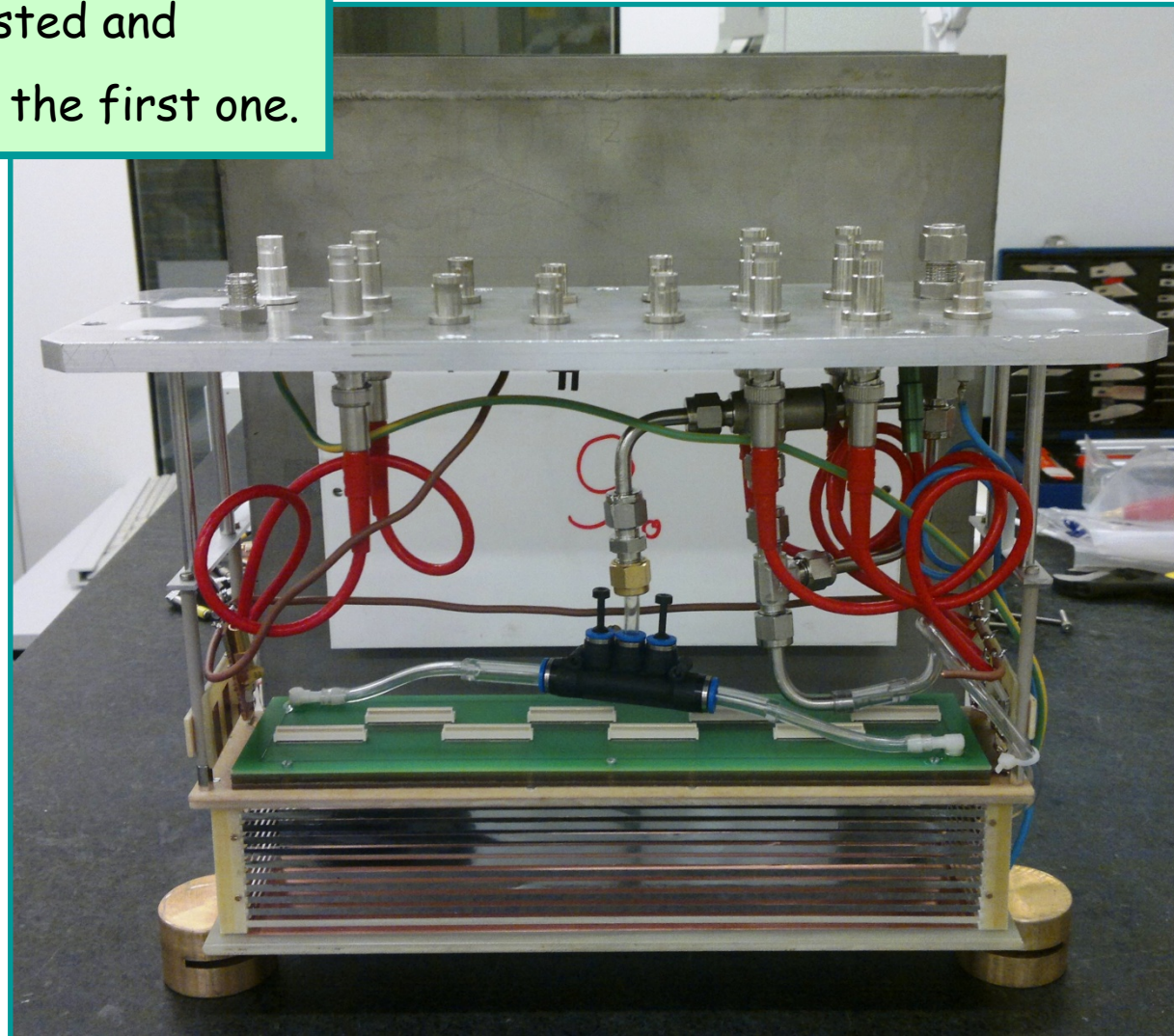


SECOND GEM-TPC PROTOTYPE HB2

The second GEM-TPC HB2 will be tested and characterized in a similar way as for the first one.

Test in the lab:

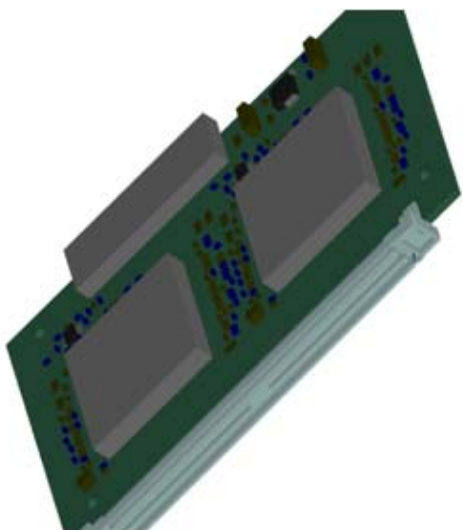
- ✓ Foils visual and scanned inspection
- ✓ Foils leakage current measurement
- ✓ Readout board capacitance measurement
- ✓ Energy resolution measurement
- ✓ Gain and its uniformity
- ✓ Oxygen concentration measurement
- ✓ Irradiation with ^{55}Fe



SECOND GEM-TPC PROTOTYPE HB2 (cont.)

GEM-TPC Readout Electronics and DAQ.

T2K FEC
developed at TUM
4 AFTER chips for
a total of 256
channels



Readout Architecture

4 x AFTER FEC

2 x ADC to USB Cards

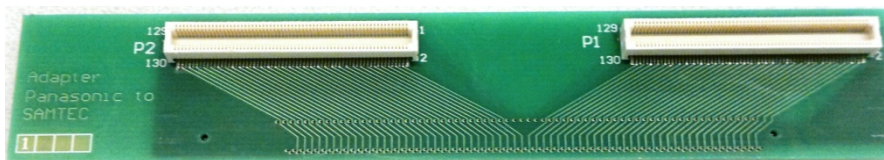


Computer

The trigger rate expected for the AFTER chip with ArCO₂ and 60 mm drift is of about 6.4 kHz. Taken into account that a total of 60 cells are needed and the clock is at 45 MHz

PAN to SAMTEC Adapter

GEM-TPC Readout board
with 1024 strips cut in the
middle

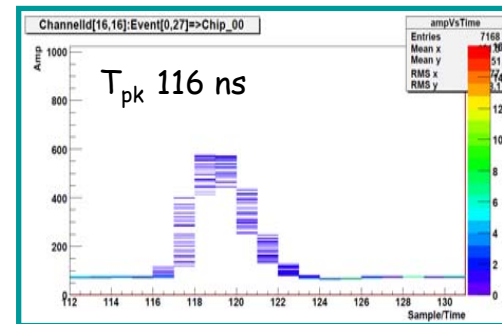


At the top a Samtec connector 300 pins
and in the left side two Panasonic
connectors of 130 pins each

SECOND GEM-TPC PROTOTYPE HB2 (cont.)

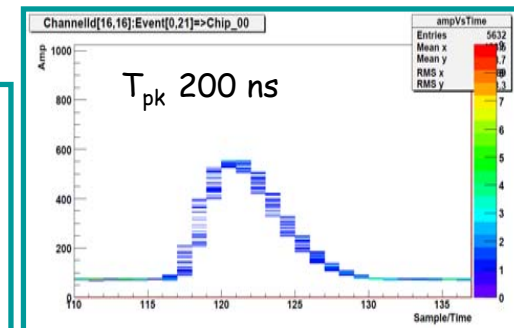
GEM-TPC readout electronics performance

Calibration
Procedure with
Test pulses
of 50 fC

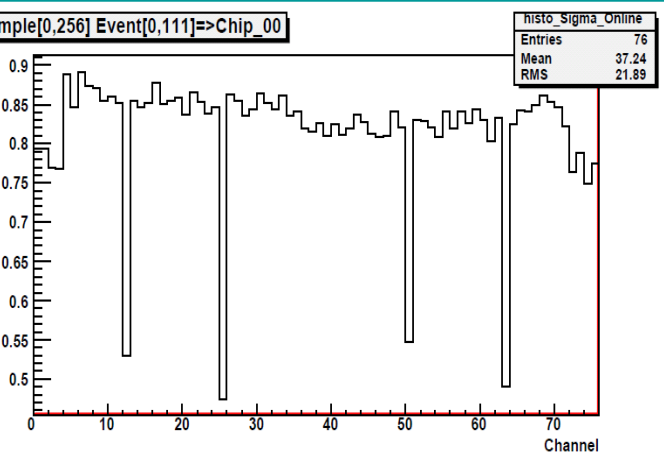
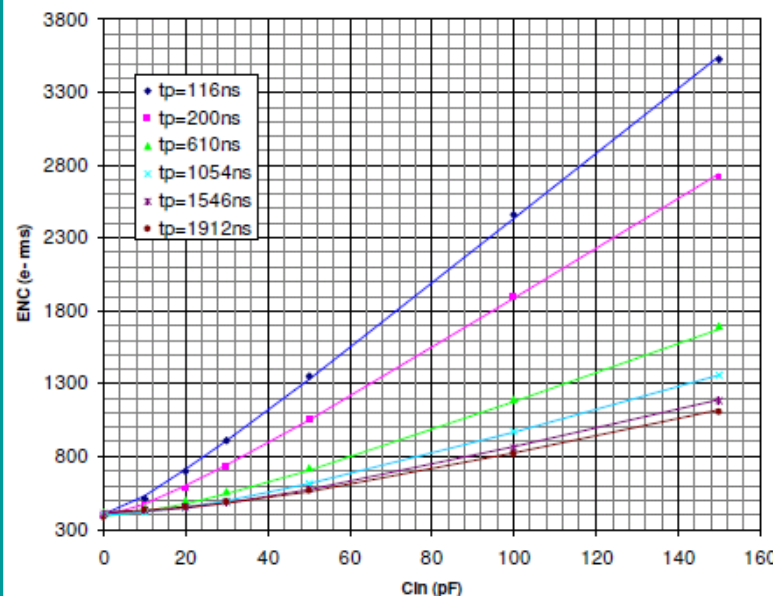


Presented by Igor Konorov
at TUM

T2K noise measured @ Saclay



Due to strips and coupled
capacitance we can expect
a 400 e⁻ noise at all the
peaking times



Test of One AFTER Chip which is wasn't
connected to the detector and has 8
channels disconnected (the first and the
last 4).

There is a fixed pattern with 4 noisy
channels.

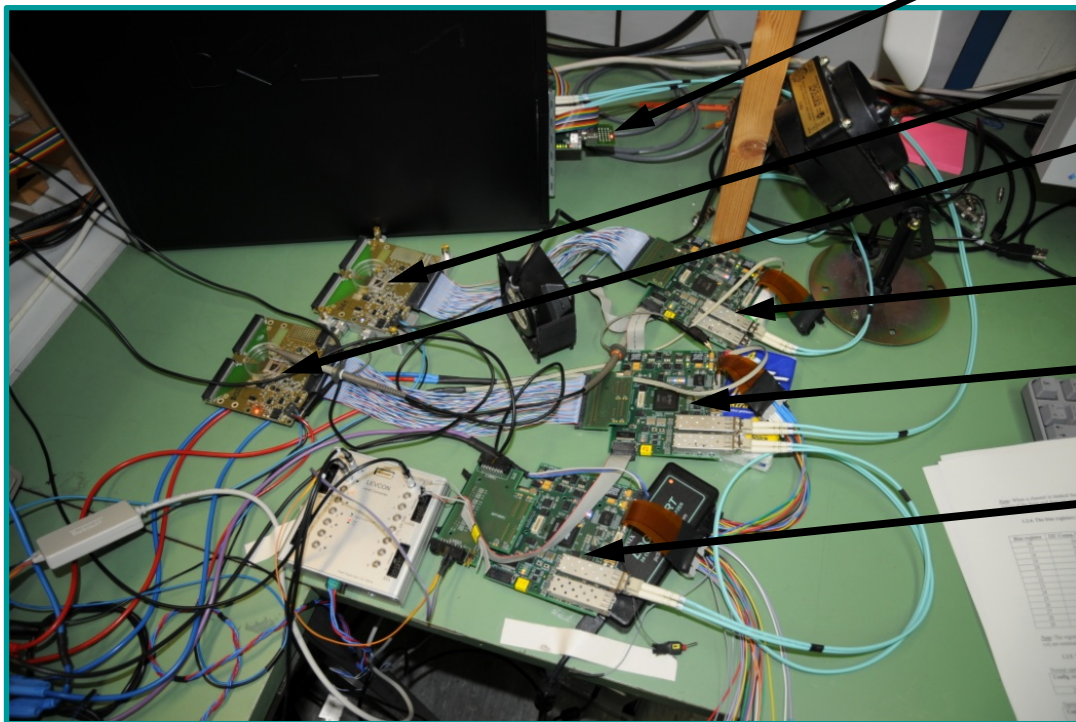
Related to the signal amplitude 1 ADC
count correspond to 0.12 fC or 700 e⁻

THIRD GEM-TPC PROTOTYPE HB3(cont.)

GEM-TPC Readout Electronics and DAQ.

Presented by Dr. Christian Schmidt at GSI

XYTER readout Architecture



PEXOR & TRIXOR

nXyter Boards

#0

#1

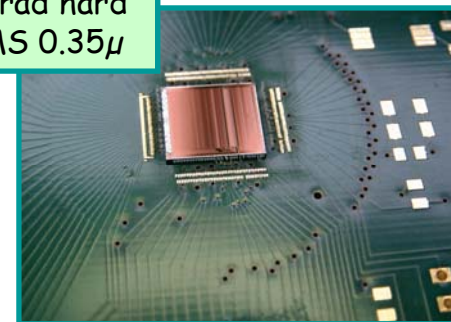
Exploder Boards

#0

#1

#2 (Source of 32 MHz)

n-XYTER,
non rad hard
AMS 0.35 μ



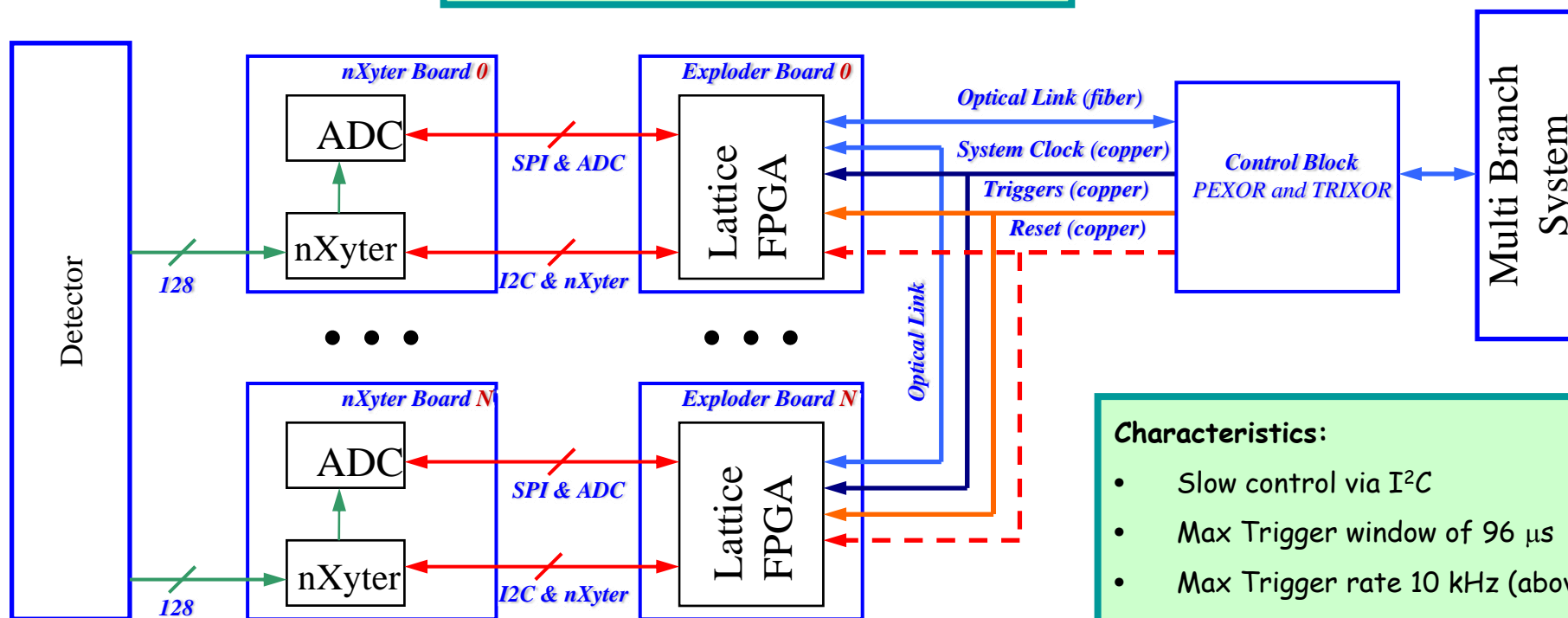
- Detector operation with purely data driven, self triggered readout
- engineering run prepared by H.K. Soltveit, PI Heidelberg

THIRD GEM-TPC PROTOTYPE HB3 (cont.)

GEM-TPC Readout Electronics and DAQ.

Presented by Dr. Ivan Rusanov at GSI

nXYTER readout Architecture



Characteristics:

- Slow control via I²C
- Max Trigger window of 96 μ s
- Max Trigger rate 10 kHz (above trigger window)

ACTIVE DIVIDER FOR GEM-TPC

GEM-TPC Active Divider

Presented by Dr. Fabrizio Murtas at INFN

Main characteristics:

-Standard NIM two units.

-USB & CAN-OPEN protocol communication interface.

-It has 7 independent channels with full isolation at 5kV to Ground.

With 6 channels from 0V to 700V with a max current of $150\mu\text{A}$

And

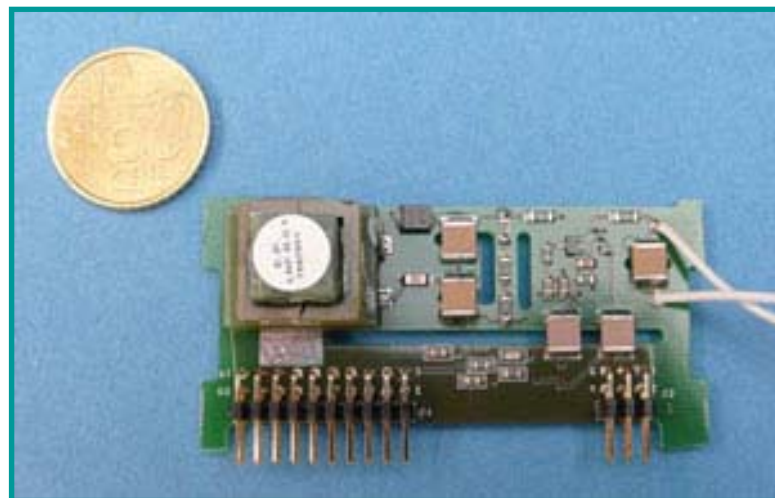
With 1 channel from 0V to 1400V with a max current of $100\mu\text{A}$

One Channel Module With dual current limit:

In the low range from 10nA up to $6\mu\text{A}$ with a resolution of 40 nA

And

With the high range from 100nA up to $40\mu\text{A}$, with a resolution of 40 nA



HV GEM module with High Current sensitivity

ACTIVE DIVIDER FOR GEM-TPC

GEM-TPC Active Divider

Test bench
in the lab.



HV GEM 2.0 Single

HV ON base address: 16 **CURMON** **EXIT**

Ramp
Vg1 (Volt): 530 G1: 529 Ramp: 20
Vg2 (Volt): 530 G2: 529 Gain: 1588
Vg3 (Volt): 530 G3: 530 current: 300

standby & field **Apply**

Drift (kV/cm): 0.0 Vd: 0 Ed: 0.0
T1 (kV/cm): 3.5 Vt1: 651 Et1: 2.2
T2 (kV/cm): 3.5 Vt2: 635 Et2: 2.1
Ind (kV/cm): 5.0 Vi: 786 Ei: 2.6

Drift Gap (mm): 1 Gap 1 (mm): 3 Gap 2 (mm): 3 Ind Gap (mm): 3
appended path: C:\Program Files (x86)\...
Write to file

Fields [KV/cm] **GEM** **Gain**

HVMON EI: 786 G3: 530 ET2: 635 G2: 529 ET1: 651 G1: 529 ED: 0
time: 99496981

The interface is very user friendly in order to control Voltages across the GEMs and the fields in between GEMs. In addition to that the current through the GEMs can be monitored



OPEN QUESTIONS

- Characterization of the GEM foils defects and its uniformity
- Field Uniformity mapping for the Field cage with different strips pitch, strips widths and for single and double strips versus different field gradients
- Optimization of the Field cage for larger Drift length
- Studies on the Ion feedback - simulations and experiment
- Calculations of Charge up effects and Gain from simulations
- Readout electrode geometry optimizations for different ions types, momenta and count rate
- Signal induction for different type of gases based on ArCO_2 with CF_4 and other gas mixtures.



TODO

- Finalizing the Second and Third Prototypes. Lab. and beam tests
- Integration of the AFTER readout electronics into HB2 and setup of the DAQ
- Integration of the Xyter readout electronics into HB3 and setup of the DAQ
- Obtain the tracking parameters like: track resolution in X and Y and maximum count rate for HB2 and HB3
- Participate in the Beam campaigns of GPAC at GSI, RD51 at CERN and Jyväskylä
- Test the HB2 and HB3 for larger than 60 mm Drift length
- Analysis of simulations in order to set clear optimizations
- Establish road map for the development of the Full side Prototype